WHAT IS CLAIMED IS:

1. A packaged semiconductor device, comprising:

an embossed carrier tape having a pocket and a protruding feature in said pocket;

a semiconductor device having a top surface and a bottom surface, said semiconductor device including an indentation in the bottom surface, said protruding feature of said embossed carrier tape interlocked in said indentation in the bottom surface of said semiconductor device.

2. The packaged semiconductor device of Claim 1, further comprising a cover over said pocket, said cover in contact with said top surface of said semiconductor device.

3. The packaged semiconductor device of Claim 1, wherein said pocket comprises a base having a pedestal formed thereon, said protruding feature on said pedestal.

4. The packaged semiconductor device of Claim 1, wherein said indentation extends from said bottom surface to said top surface of said semiconductor device.

5. The packaged semiconductor device of Claim 1, wherein said indentation is in the range of about 0.1 mm to about 0.32 mm in depth.

6. The packaged semiconductor device of Claim 1, wherein said indentation is one of a plurality of indentations in said bottom surface arranged in a pattern, and said embossed carrier tape comprises a pocket having a plurality of protruding features in an arrangement corresponding to said pattern of indentations in said bottom surface of said semiconductor device.

7. A method of packing a semiconductor device, said method comprising the steps of:

providing a semiconductor device having a top surface and a bottom surface, said semiconductor device including an indentation in the bottom surface;

providing an embossed carrier tape having a pocket of a size sufficient to accommodate said semiconductor device, a protruding feature in said pocket of size and dimension to interlock with said indentation in the bottom surface of said semiconductor device;

placing said device in said pocket so that the protruding feature in said pocket interlocks with said indentation in the bottom surface of said semiconductor device; and

covering said pocket.

8. The method of Claim 7, wherein said step of covering said pocket comprises covering said pocket with a tape.

9. The method of Claim 8, wherein said tape is placed in contact with said top surface of said semiconductor device.

10. The method of Claim 7, wherein said step of providing a semiconductor device comprises providing a semiconductor device comprising a plurality of said indentations in said bottom surface, and said step of providing an embossed carrier tape comprises providing a carrier tape comprising a pocket having a plurality of protruding features in an arrangement corresponding to the plurality of said indentations in said bottom surface of said semiconductor device.

11. The method of Claim 7, wherein said step of providing a semiconductor device comprises providing a semiconductor device having an indentation extending from said bottom surface to said top surface of said semiconductor device.

12. The method of Claim 7, wherein said step of providing an embossed carrier tape comprises providing a carrier tape comprising a pocket having a base, said pocket further comprising a pedestal at said base, said protruding feature on said pedestal.